

	Type	Hits	Search Text	DBs
99	BRS	243	hiatt-w\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
100	BRS	1	S144 and S103	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
101	BRS	1732	farnworth-w\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
102	BRS	696	hembree-d\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
103	BRS	325	S161 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
104	BRS	267	benson-p\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
105	BRS	120604	(blast or blasted or blasting or jet or jetting or jettet or direct or directing or directed or applying or applied or apply) adj10 (fluid or liquid or air or vapor or gaseous or pressure or pressurizing or pressurized) adj10 (surface or substrate or wafer or silicon or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
106	BRS	2453	S99 or S100 or S101 or S102	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
107	BRS	247	(stereolithograph\$) with (unconsolidat\$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
108	BRS	111	S112 and ((pressur\$6) adj10 (jet or jetting or jetted or nozzle))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
109	BRS	370038	(blast or blasting or blasted or direct or directing or directed or treat or treating or treated) with (pressure or pressurized or pressurizing)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
110	BRS	147540	((direct or directing or directed or blast or blasted or blasting or jet or jetting or jetted) adj6 (pressure or pressurizing or pressurized) or air adj3 knife)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
111	BRS	97	S168 with S172	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
112	BRS	18	S173 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
113	BRS	178415	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened) with (unconsolidat\$ or photopolymer or polymer or polymeric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
114	BRS	678	S105 with S106	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
115	BRS	1	S104 and S107	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
116	BRS	17831	S131 with S132	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
117	BRS	0	("2004/0159340").URPN.	USPAT
118	BRS	0	S105 and S106 and S104	USPAT
119	BRS	14	S105 and S106 and (stereolithograph\$)	USPAT
120	BRS	343191	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened or flush or flushing or flushed or dislodge or dislodging or dislodged) adj10 (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination) with (surface or substrate or wafer or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
121	BRS	2	"4903717".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
122	BRS	188527	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened or flush or flushing or flushed or dislodge or dislodging or dislodged) adj10 (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination or mold or molded or resin) adj10 (wafer or substrate or surface or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
123	BRS	244204	("134"/\$ or "438"/\$).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
124	BRS	2	"6616768".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
125	BRS	8	S114 and (blast or blasted or blasting)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
126	BRS	41	S114 and (nozzle or jet or jetted or jetting)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
127	BRS	162	S112 with (pressure or pressurized or pressurizing)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
128	BRS	0	S114 with (blast or blasted or blasting)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
129	BRS	3054	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened) with (excess\$4) adj10 (unconsolidat\$ or photopolymer or polymer or polymeric)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
130	BRS	59	S112 and S103	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
131	BRS	6	S121 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
132	BRS	52618	"134"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
133	BRS	180	S125 with S126	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
134	BRS	4	"6247479".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
135	BRS	0	S127 and (stereolithograph\$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
136	BRS	9	("20010032111" "20030114016" "3889355" "4027246" "4728252" "5789890" "6336204" "6337122" "6463349").PN.	US-PGPUB; USPAT
137	BRS	282867	(pressure or pressurized or pressurizing) with (nozzle or jet or jetting or jetted)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
138	BRS	33	S149 and S134	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
139	BRS	13	S127 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
140	BRS	11692	(pressure or pressurizing or pressurized) with S138	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
141	BRS	813	S144 with S146	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
142	BRS	4507	S133 and (vacuum or negative adj3 pressure or air adj3 knife or positive adj3 pressure)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
143	BRS	2021587	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened or blast or blasted or blasted or jet or jetting or jetted or contact or contacting or contacted) adj10 (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
144	BRS	260514	(blast or blasted or blasting or jet or jetting or jett\$ or direct or directing or directed or applying or applied or apply adj10 (fluid or liquid or air or vapor or gaseous or pressure or pressurizing or pressurized) with (surface or substrate or wafer or silicon or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
145	BRS	176448	((pressur\$6) adj10 (jet or jetting or jett\$ or nozzle))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
146	BRS	58862	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened) with (excess\$4) adj10 (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
147	BRS	163	S148 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
148	BRS	2032	S144 and S146	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
149	BRS	21371	S136 with S138	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
150	BRS	15	S134 and (stereolithograph\$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
151	BRS	7135	S159 with S152	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
152	BRS	2128	S160 with (pressure or pressurizing or pressurized or positive adj3 pressure or negative adj3 pressure or air adj3 knife)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
153	BRS	4415	S153 with (pressure or pressurizing or pressurized or positive adj3 pressure or negative adj3 pressure or air adj3 knife)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
154	BRS	1698	S163 adj10 (pressure or pressurizing or pressurized or positive adj3 pressure or negative adj3 pressure or air adj3 knife)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
155	BRS	326	S159 with S167	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
156	BRS	4741	(blast or blasted or blasting or jet or jetting or jetted or direct or directing or directed or applying or applied or apply adj10 (pressure or pressurized or pressurizing) adj10 (fluid or liquid or air or vapor or solvent or water or "H2O" or "H.sub.20") adj10 (surface or substrate or wafer or silicon or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
157	BRS	79	S168 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
158	BRS	1149432	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or treat or treating or treated or treatment or wash or washing or washed or spray or spraying or sprayed or sprayer or jet or jetting or jetted or strip or stripping or stripped or etch or etching or etched) adj10 (wafer or substrate or surface or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
159	BRS	76680	(pressure or pressurized or pressurizing) adj10 (fluid or liquid or air or vapor or solvent or water or "H2O" or "H.sub.2O" or solution or mixture) adj10 (surface or substrate or wafer or silicon or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
160	BRS	1189991	(removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened or flush or flushing or flushed or dislodge or dislodging or dislodged) adj10 (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination or mold or molded or resin or residue or residual)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
161	BRS	6060	(blast or blasted or blasting or jet or jetting or jettet or direct or directing or directed or applying or applied or apply or spray or spraying or sprayed) adj10 (pressure or pressurized or pressurizing) adj10 (fluid or liquid or air or vapor or solvent or water or "H2O" or "H.sub.2O" or solution or mixture) adj10 (surface or substrate or wafer or silicon or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
162	BRS	566	S181 with S182	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
163	BRS	64009	S175 with S172	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
164	BRS	5626	S137 with S138	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
165	BRS	103	S159 with S164	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
166	BRS	6132	S142 with S143	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
167	BRS	2322331	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened or flush or flushing or flushed or dislodge or dislodging or dislodged) with (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
168	BRS	0	S99 with S138 with S139	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
169	BRS	56550	(blast or blasted or blasting or jet or jetting or jetted) with (fluid or liquid or air or vapor or gaseous) with (surface or substrate or wafer or silicon or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
170	BRS	558518	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened or blast or blasted or blasted or jet or jetting or jetted or contact or contacting or contacted) adj10 (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination) with (surface or substrate or wafer or silicon or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
171	BRS	175257	(pressure or pressurized or pressurizing) adj10 (nozzle or jet or jetted or jetting)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
172	BRS	23	S165 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
173	BRS	13827	S151 with S152	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
174	BRS	23458	S156 with S152	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
175	BRS	8506	S157 with (pressure or pressurizing or pressurized or positive adj3 pressure or negative adj3 pressure or air adj3 knife)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
176	BRS	626775	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened or flush or flushing or flushed or dislodge or dislodging or dislodged) with (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination or mold or molded or resin) with (wafer or substrate or surface or semiconductor)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
177	BRS	156	S177 with S172	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
178	BRS	45562	(blast or blasted or blasting or jet or jetting or jetted or direct or directing or directed or applying or applied or apply or spray or spraying or sprayed) with (pressure or pressurized or pressurizing) with (fluid or liquid or air or vapor or solvent or water or "H2O" or "H.sub.2O" or solution or mixture) adj10 (surface or substrate or wafer or silicon or semiconductor or workpiece)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
179	BRS	114	S183 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
180	BRS	37	S178 and S123	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Type	Hits	Search Text	DBs
181	BRS	2527646	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or remove or removing or removed or removal or eliminate or eliminating or eliminated or elimination or strip or stripping or stripped or stripper or loosen or loosening or loosened or flush or flushing or flushed or dislodge or dislodging or dislodged) with (unconsolidat\$ or photopolymer or polymer or polymeric or material or contaminant or particle or particulate or liquid or fluid or impurity or soil or soiling or soiled or foreign adj5 (matter or material) or dirt or contamination or mold or molded or resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
182	BRS	2444	S175 with S176	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB
183	BRS	5	("5529636").URPN.	USPAT